

# LASER THERMAL

## SSTR-F

- ✓ Thermal Conductivity Measurement System
- ✓ 150 mm x 150 mm scanning stages
- ✓ From room temperature up to 200 degrees C
- ✓ Dual laser thermoreflectance measurements

## APPLICATIONS

### CLASS I SSTR-F SYSTEM

- ✓ Thin film oxide films
- ✓ Metals, nitrides, and alloys
- ✓ Wide band gap semiconductors
- ✓ Polymers and photoresists
- ✓ ALD thin films

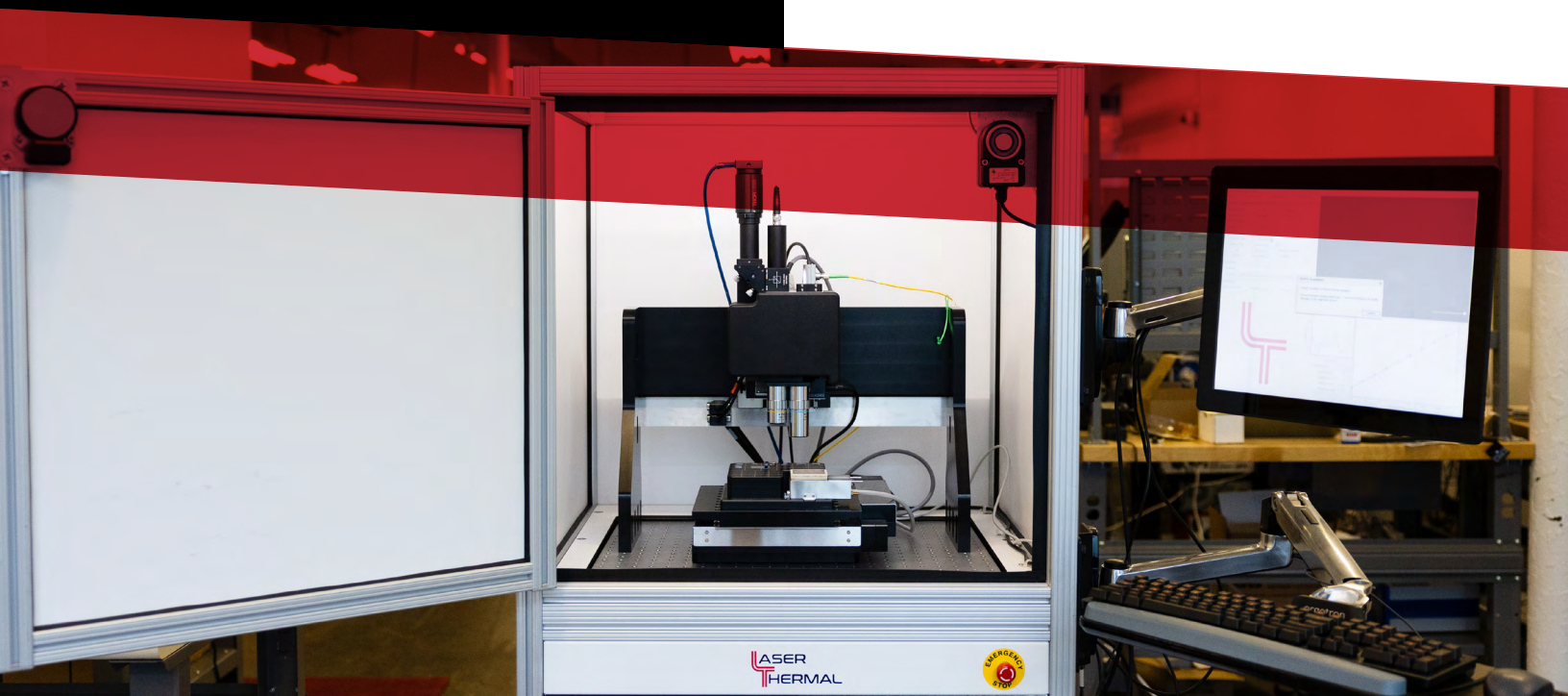
## SPECIFICATIONS

The SSTR-F system offers a first-of-its-kind thermoreflectance-based thermal property measurement system developed to meet the needs of research and development groups.

The fully-automated system brings the power of thin-film and small-volume thermal measurements from the academic lab to the industrial R&D setting. Laser Thermal's patented fiber optic delivery system offers unprecedented repeatability and speed to handle high volume R&D testing for screening of materials, thermal conductivity measurements, small-scale thermal mapping, and testing at elevated temperatures. Automated focus and sample alignment give researchers the ability to measure thermal resistance of films and thermal conductivity of materials with the push of a button.

With intuitive analysis software, SSTR-F offers a variety of analysis options, from traditional bulk measurements, thin-film thermal resistance measurements, thin-film thermal conductivity measurements, and quantitative maps of relative thermal properties at length scales down to sub-micron.

SSTR-F is the ideal machine to develop and perfect material choices used in a range of applications.



## BASIC FEATURES



### SAMPLE SIZE

Coupons from 5 mm up to 6-inch diameter wafers with automated motion stage



### THICKNESS RANGE

Thermal resistance measurements for thin films as thin as 1 nm; thermal conductivity for most films thicker than 100 nm up through bulk materials



### CONTROL

Full PC control with automated focus and sample alignment for turn-key testing; multi-sample batch testing



### SAFETY

Class I and Class IIIb Laser Product. SSTR-F can be fully integrated into a laser safety enclosure to become compliant as a Class I Laser Product

## ADDITIONAL FEATURES



### MOTION STAGE

Up to 150 mm x 150 mm motion stage. Enables full automation with batch routines up to 30 samples (10 mm x 10 mm) at a time; allows for large scale thermal mapping of sample surfaces



### TEMPERATURE STAGE

From room temperature up to 200C for up to four 10 mm x 10 mm samples



### AUTOMATED OBJECTIVE SWITCHING

Increased automation to measure samples with two probing volumes, offering additional sensitivities to thermal properties

## PHYSICAL SPECIFICATIONS

### Facilities

- Voltage: 110V/220V, 50/60Hz
- Power: 1 kW

### Dimensions and Weight

- Width: 31 in
- Depth: 32 in
- Height: 69 in
- Weight: 500 lbs

## CUSTOMER SUPPORT

- ✓ Customer support available 9AM-5PM EST M-F
- ✓ Full-service contracts and extended warranties available
- ✓ Remote support available via remote login, email, and phone support
- ✓ Capability to tailor testing routines for customers

## FAQ

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### Technique Description

Steady-state thermorefectance-based optical pump-probe technique to measure the thermal conductivity of materials using a continuous wave laser heat source. The technique works in principle by inducing a steady-state temperature rise in a material via long enough exposure to heating from a pump laser. A probe beam is then used to detect the resulting change in reflectance, which is proportional to the change in temperature at the sample surface. Increasing the power of the pump beam to induce larger temperature rises, Fourier's law is used to determine the thermal conductivity. We show that this technique is capable of measuring the thermal conductivity of a wide array of materials having thermal conductivities ranging from 1 to  $>2000 \text{ W m}^{-1} \text{ K}^{-1}$ , in excellent agreement with literature values.

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### SSTR-F

Steady state thermorefectance in fiber optics

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### Scanning Capabilities

Spot measurements, thermal mapping (user defined pixel resolution)

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### Property Output

Thermal conductivity, thermal boundary resistance, interfacial thermal resistance

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### Measurement Types

Cross-plane, In-plane (sample geometry dependent)

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### Length Scales / Film Thickness

Sub-micron up to tens of microns (effectively bulk)

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### Measurement Time

Less than 30 seconds per spot (thermal mapping time depends on pixel density)

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### Transducer Coating

Aluminum or gold, 80 nm thick

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### Pump Laser

Diode laser, 637 nm aluminum transducer, 532 gold transducer, frequency 10 khz, power less than 10 mW

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### Probe Laser

Diode laser, 785 nm aluminum transducer, 488 gold transducer, power less than 1 mW

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<b>Measurement Area</b>	Based on spot size
<b>Spot Size</b>	Variable diameter of 2 - 20 microns depending upon objective
<b>Penetration Depth</b>	Proportional to spot size (radius of spot size)
<b>Absorption Depth</b>	30-40 nm (in metal transducer)
<b>Temperature Range</b>	Room temperature to 300C
<b>Thermal Conductivity Range</b>	0.05 to 500 W/m/K
<b>Spatial resolution (X-Y)</b>	Down to ~ 1 micrometer
<b>Repeatability</b>	+/-1%
<b>Reproducibility</b>	+/-2%
<b>Test Sample Roughness</b>	<10 nm RMS
<b>Atmosphere</b>	Ambient (purge gas or vacuum on request)
<b>Calibration Standard</b>	Corning HPFS 7980 or thermal oxide on silicon
<b>Software</b>	Data acquisition, Data analysis, Database - Fully automated
<b>Installation &amp; Training</b>	1 day